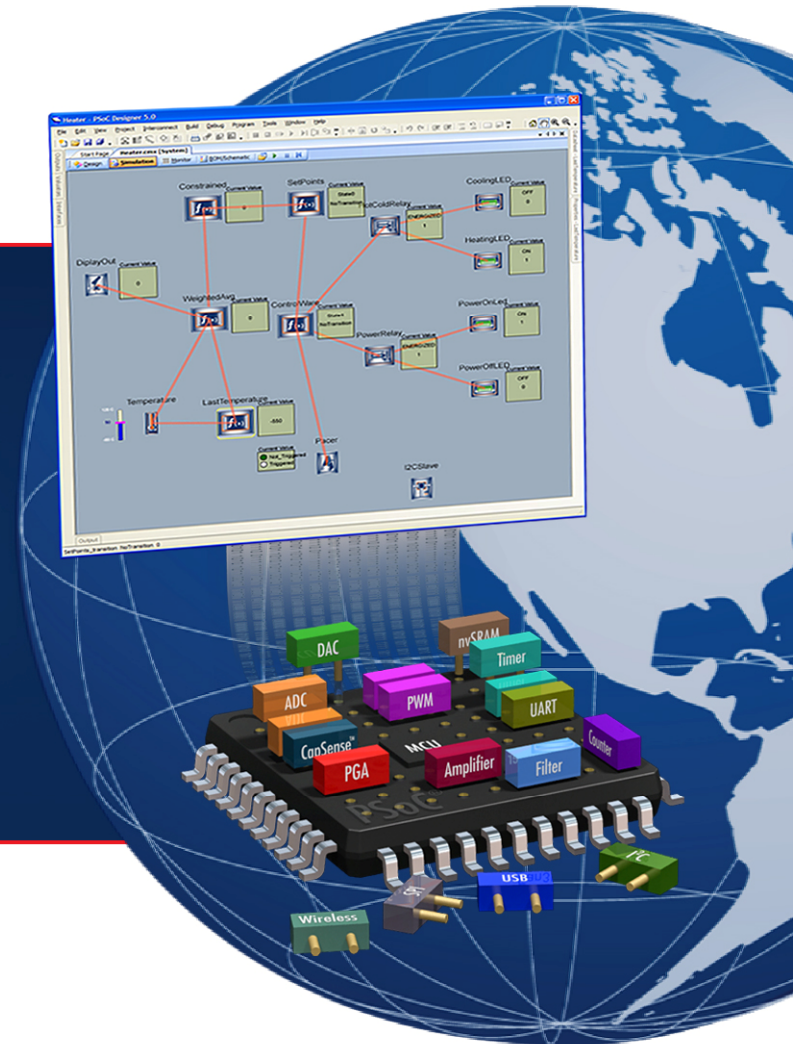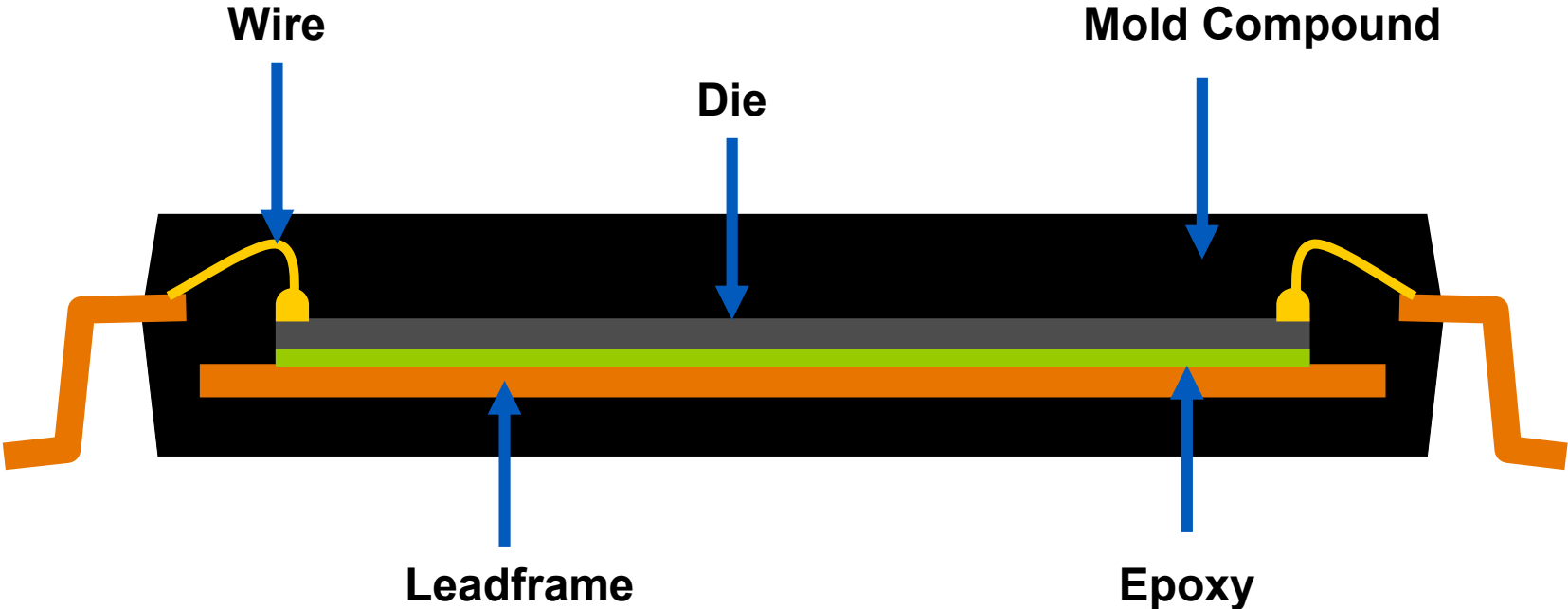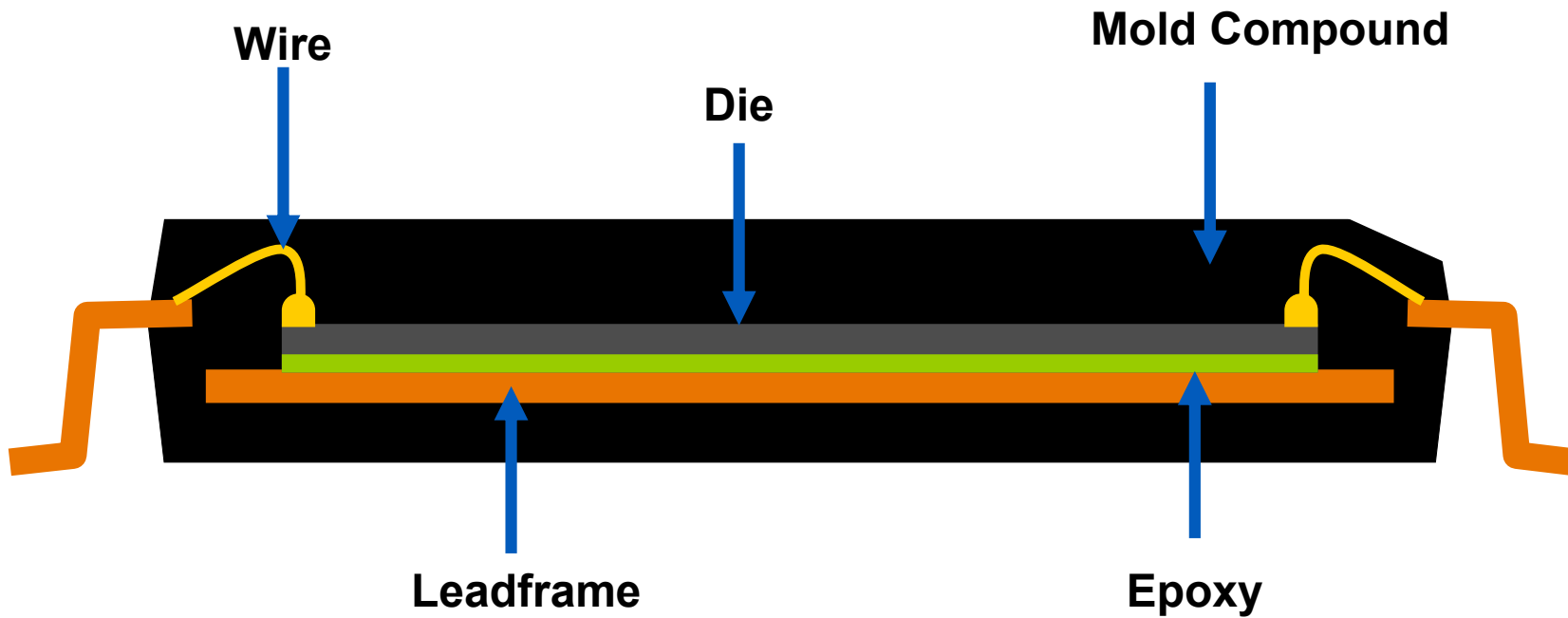# PACKAGE CROSS-SECTION DRAWINGS

February 26, 2014

Note: The purpose of this diagram is to illustrate the cross-section of Cypress products.

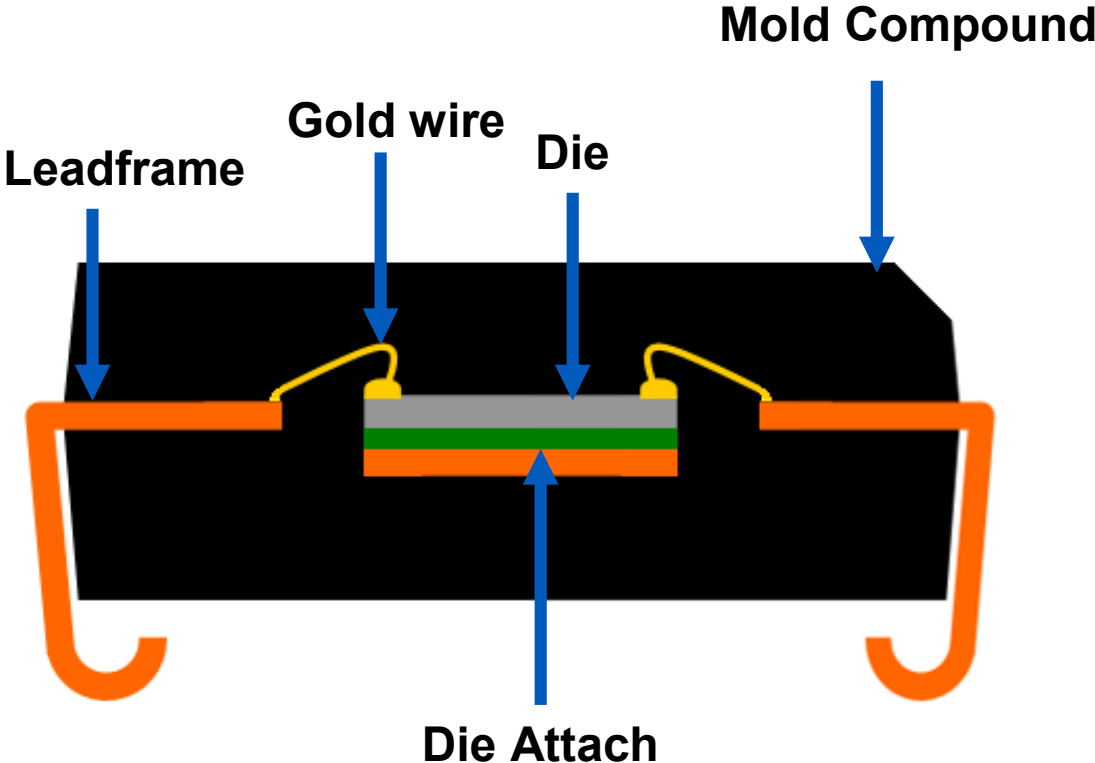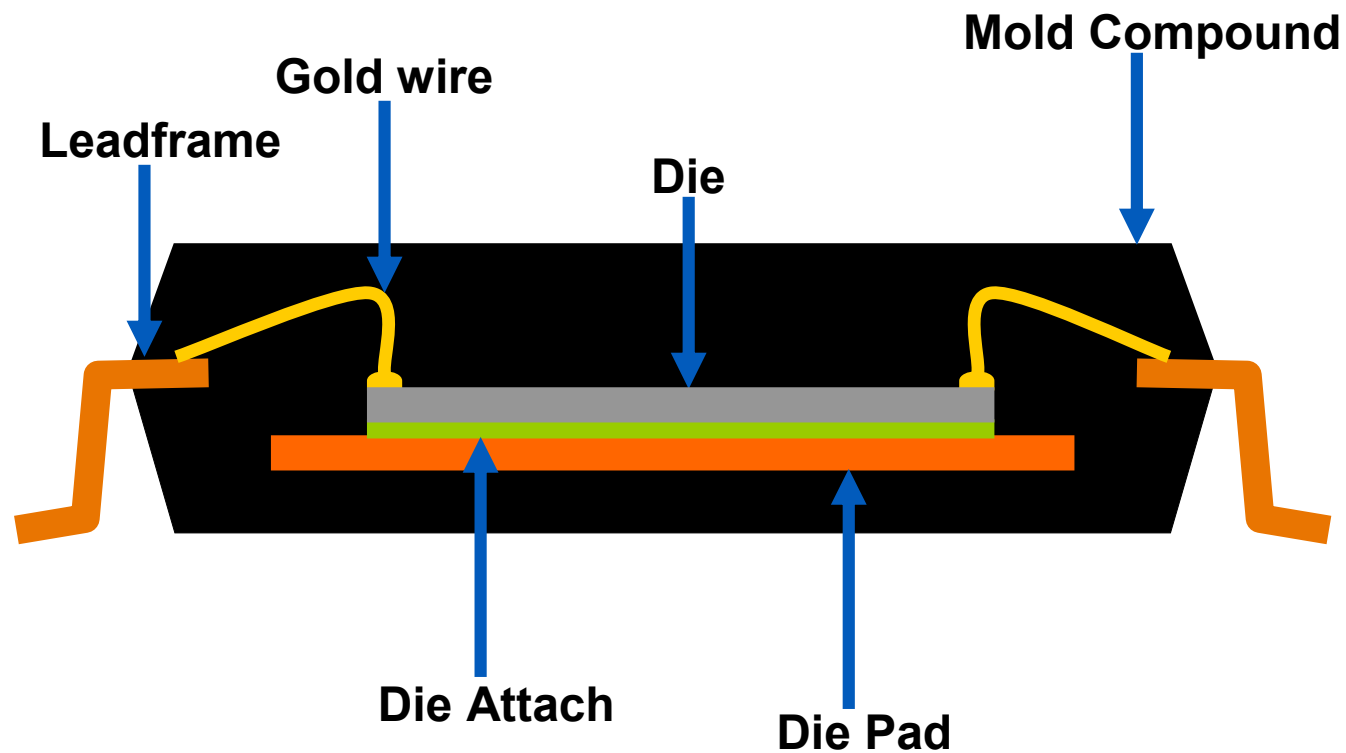# SOIC

Wire

Die

Mold Compound

Leadframe

Epoxy

SSOP

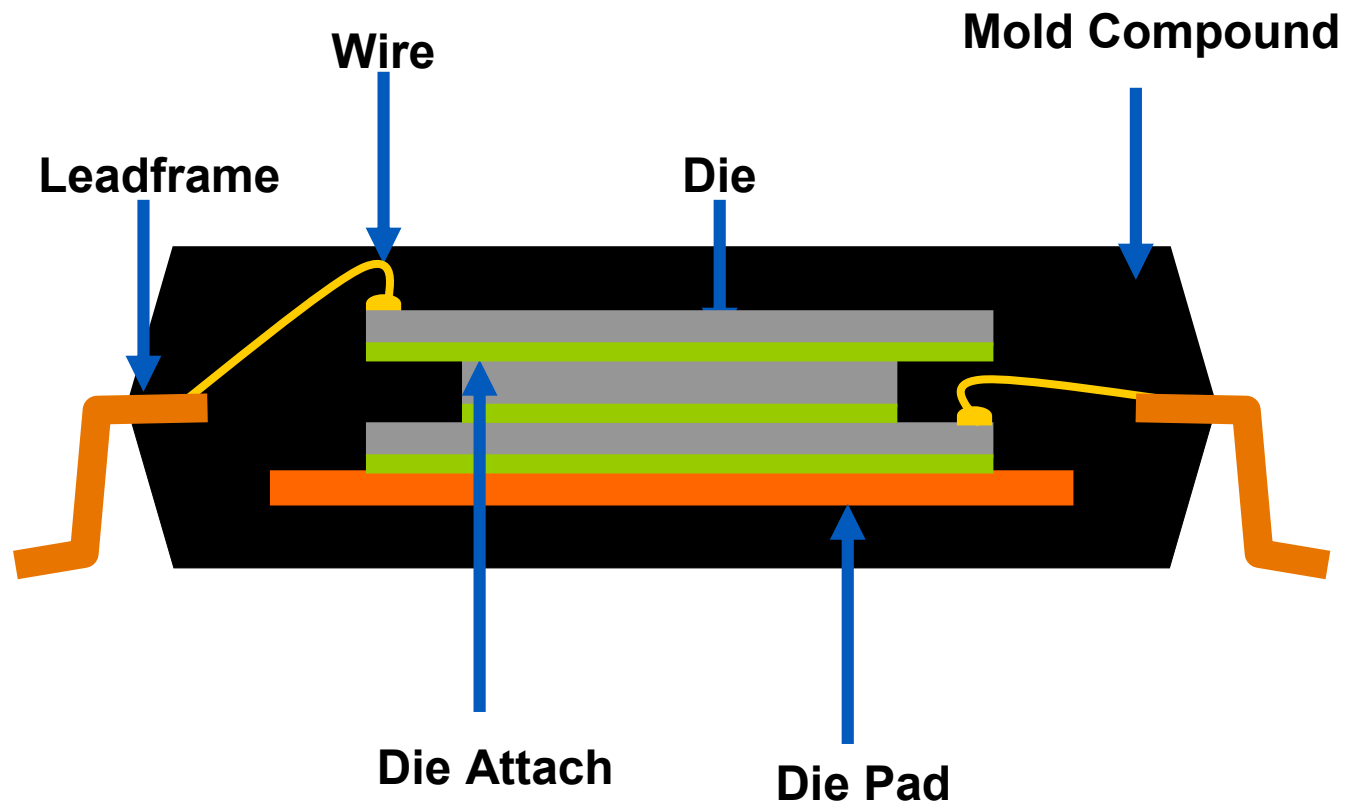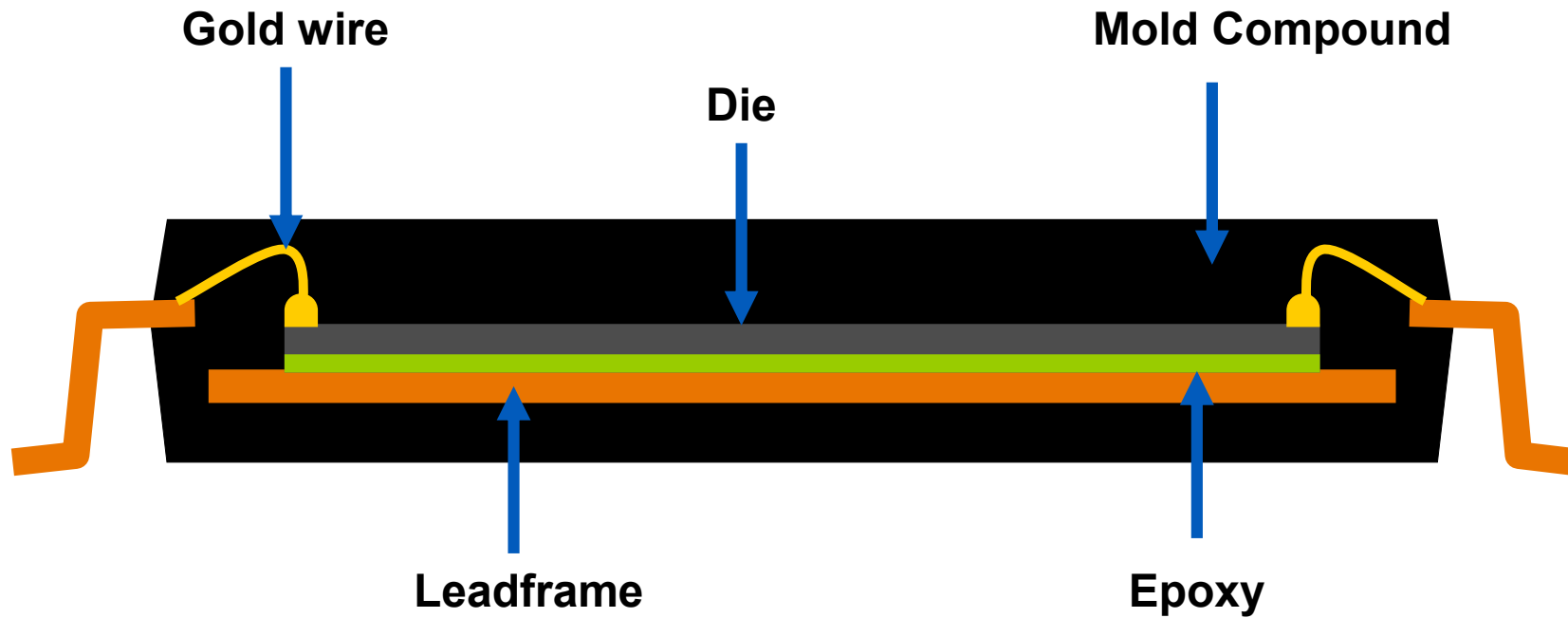# SOJ

Leadframe

Gold wire

Die

Mold Compound

Die Attach

TSSOP / TSOP

TSOP (STACKED DIE)

TQFP/PQFP

Gold wire

Mold Compound

Die

Leadframe

Epoxy

BGA

CYPRESS CONFIDENTIAL

BGA (STACKED DIE)

Wire

Mold Compound

Top Die

Spacer

Bottom Die

Epoxy / Die Attach

Solder ball

Substrate

PLCC

Mold Compound

Die

Wire

Leadframe

Die Attach

Die Pad

QFN (SAW)

CYPRESS CONFIDENTIAL

QFN (PUNCH)

Mold Compound

Die

Wire

Leadframe

Die Attach

WLCSP

Backside Laminate

Silicon Die

UBM Layer

Polyimide Layer

Lead Free Solder Ball

LCC

CERDIP

Mold Compound

Die

Wire

Leadframe

Die Attach
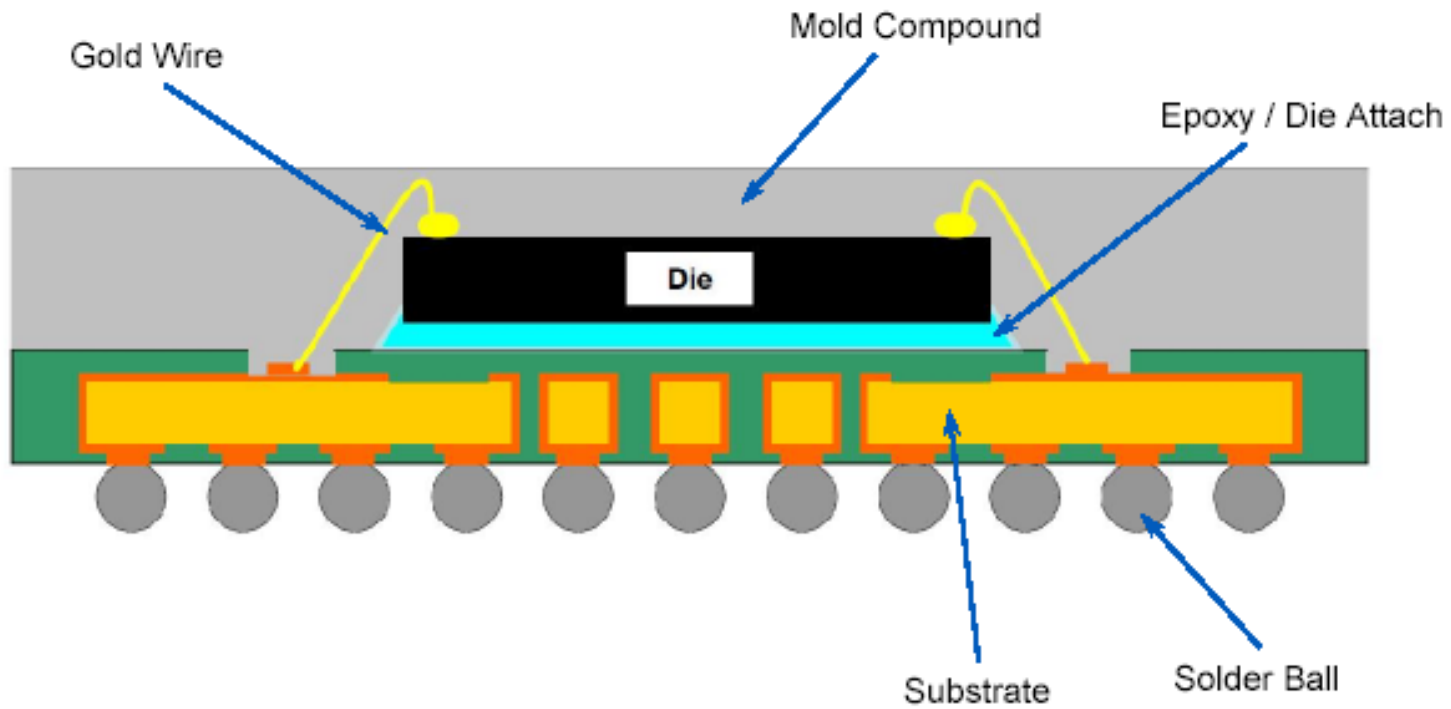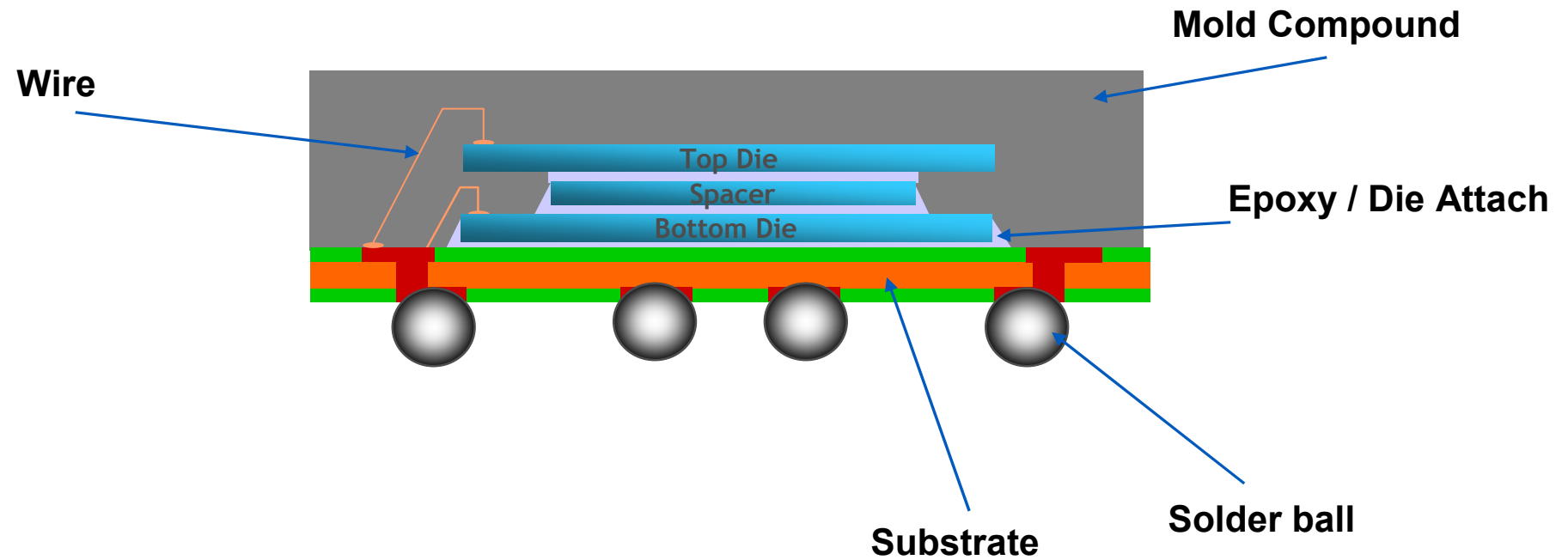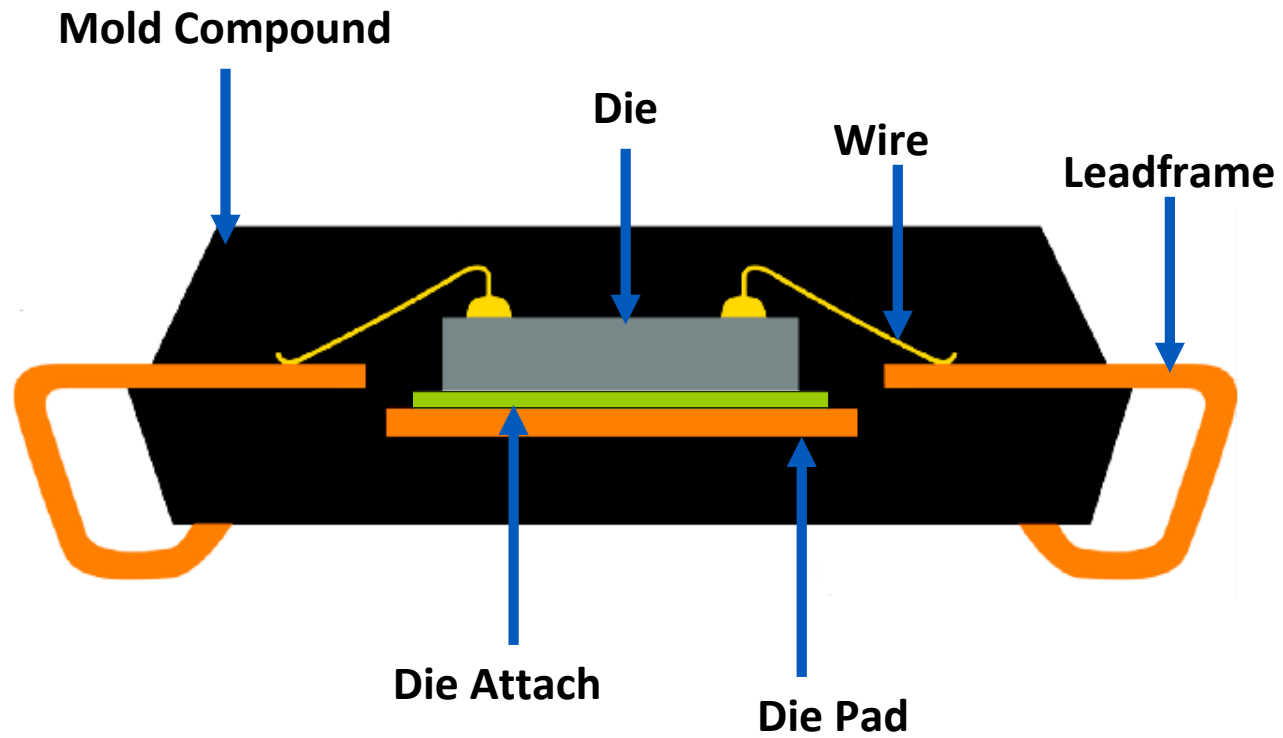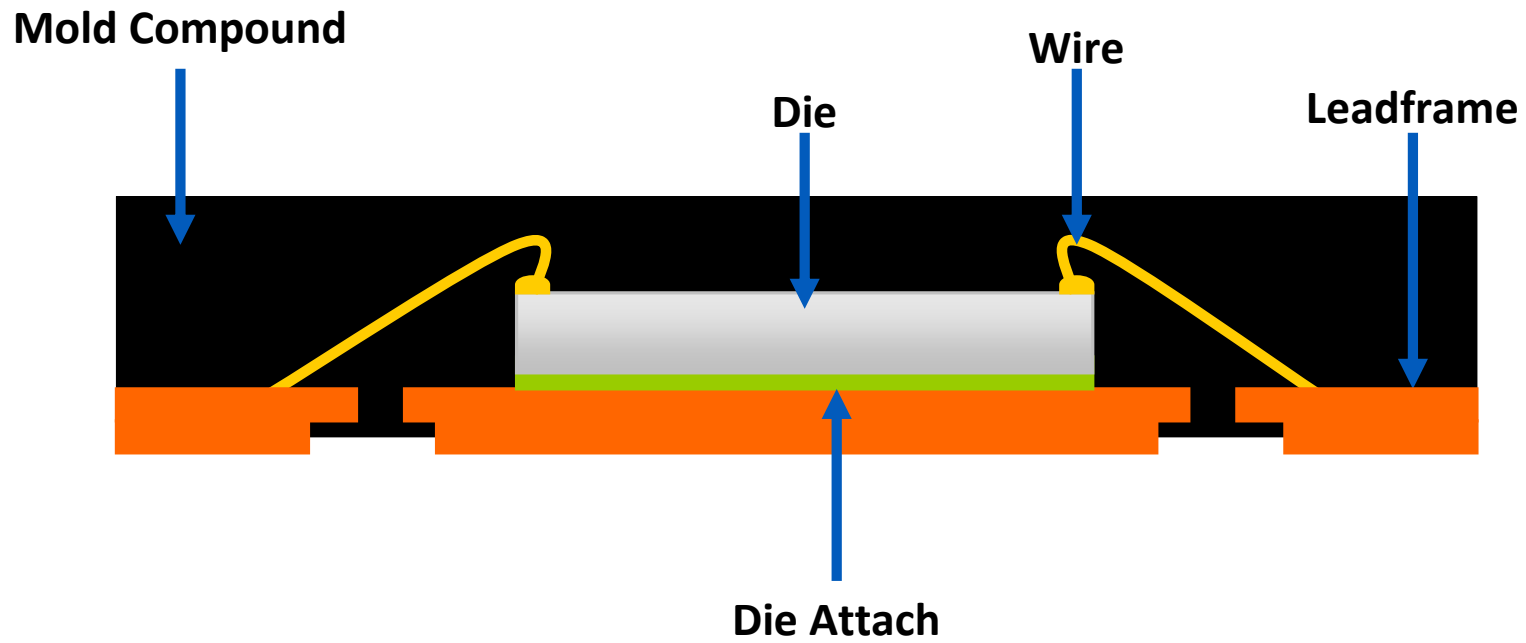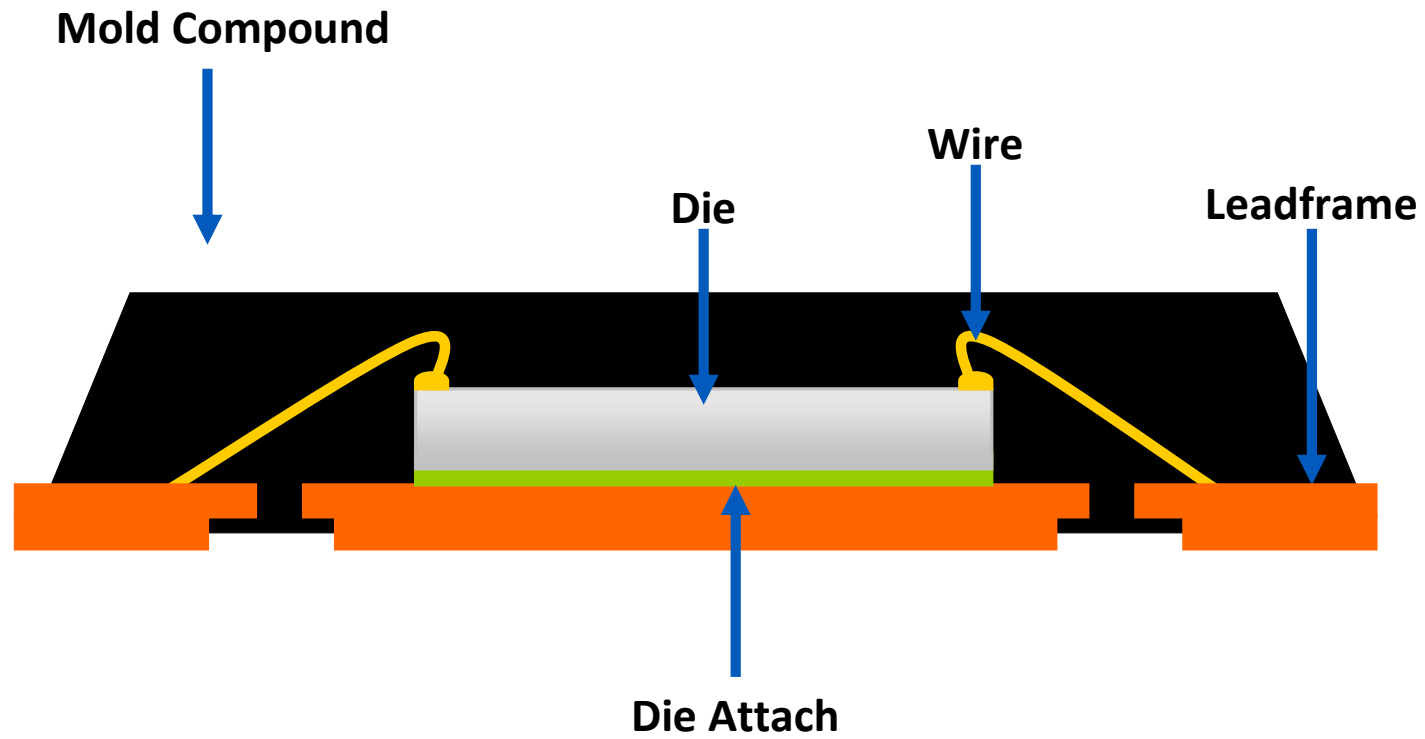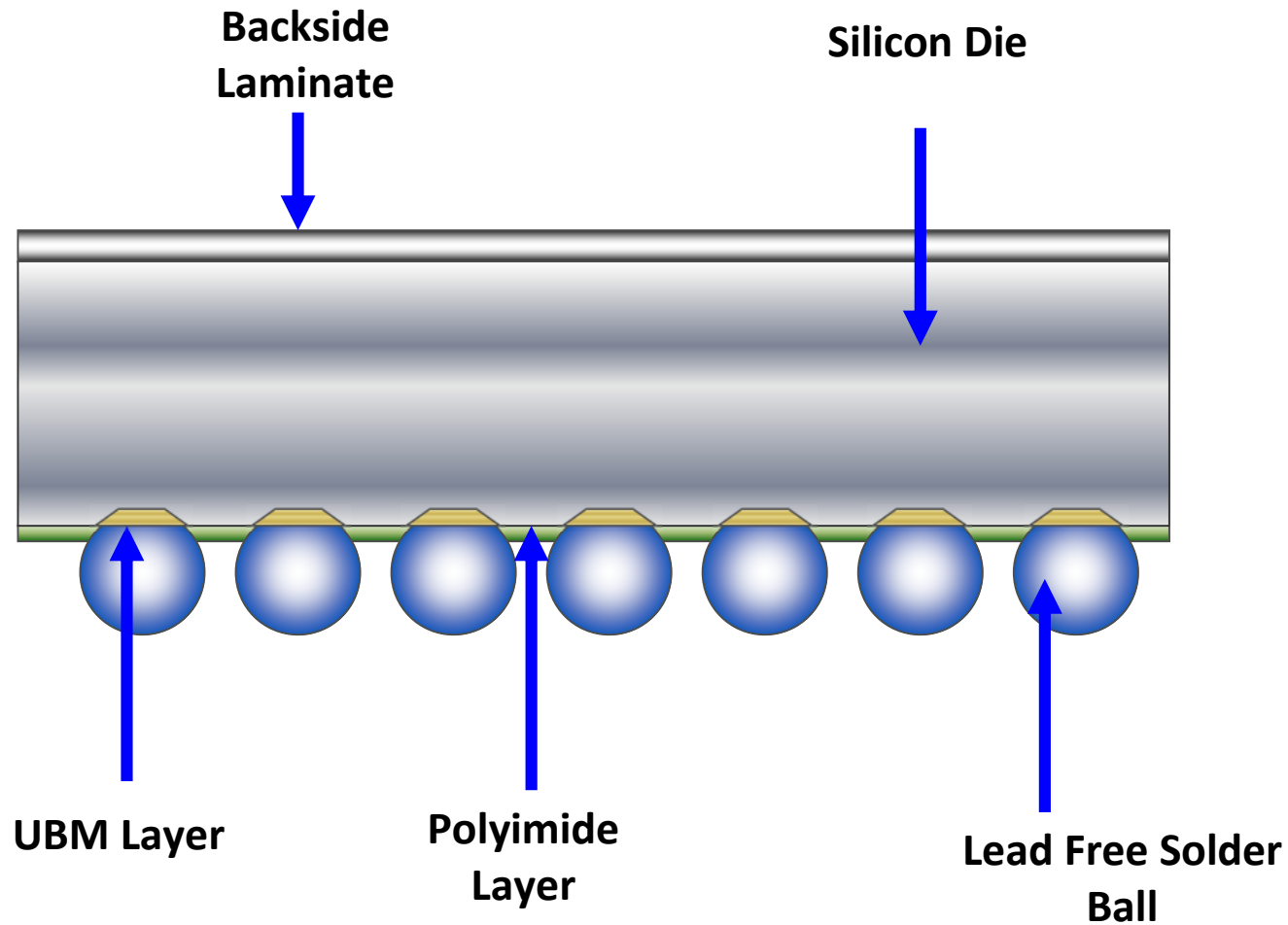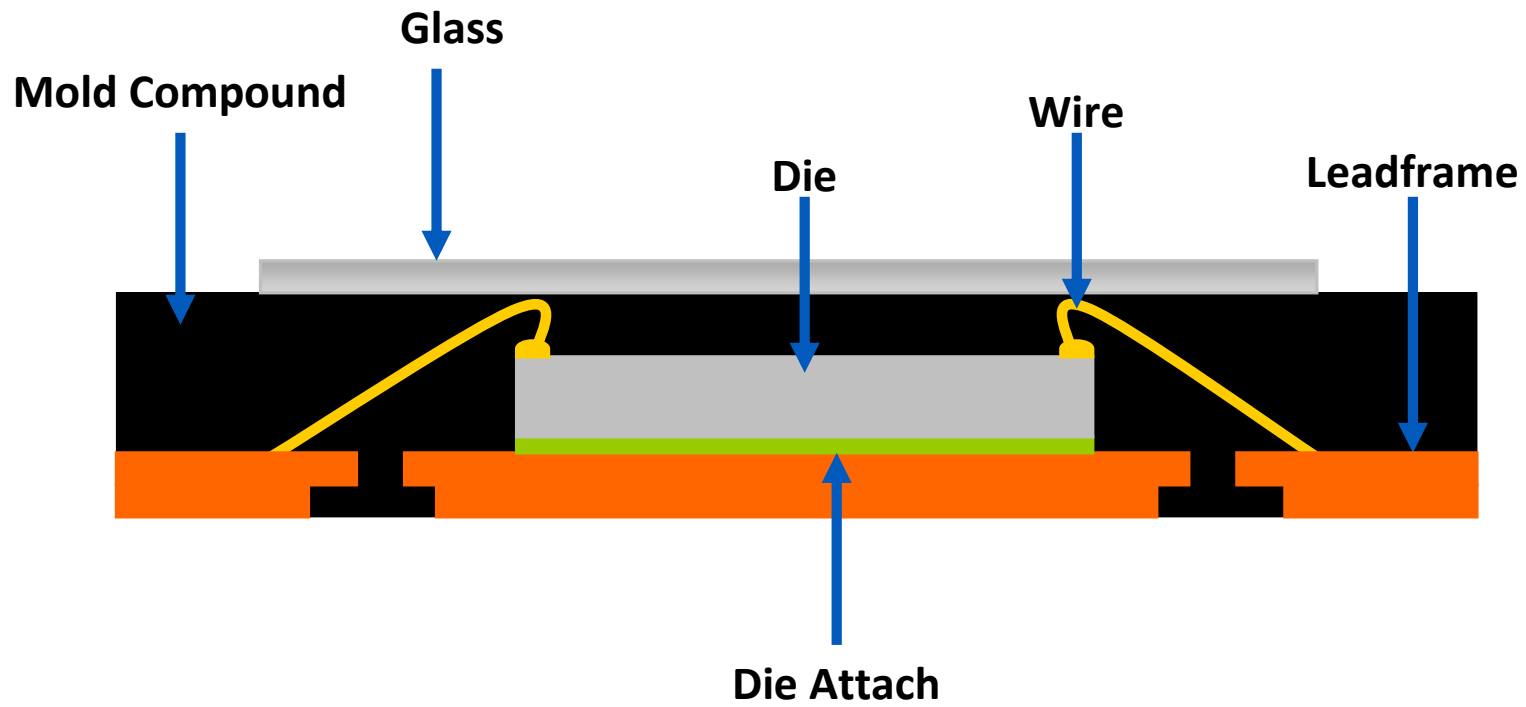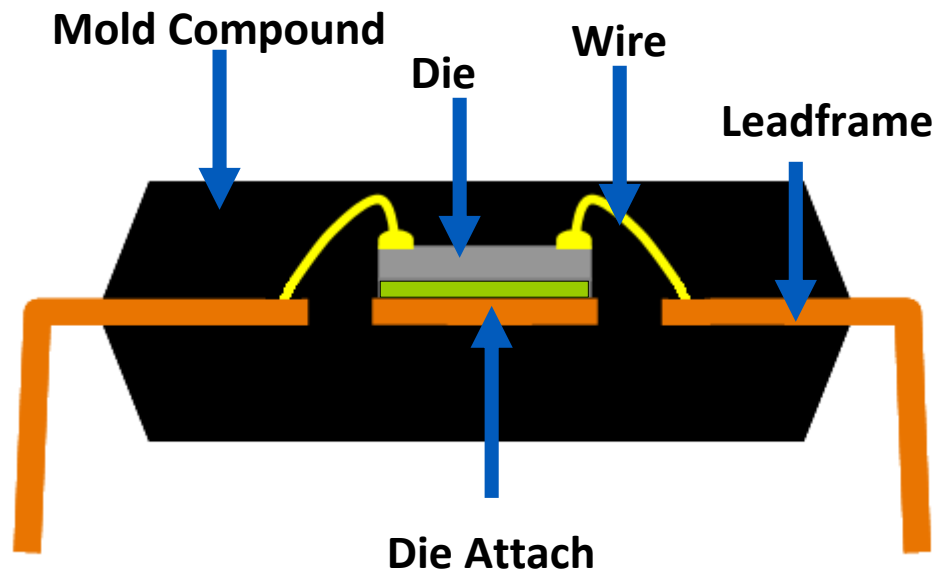
PGA
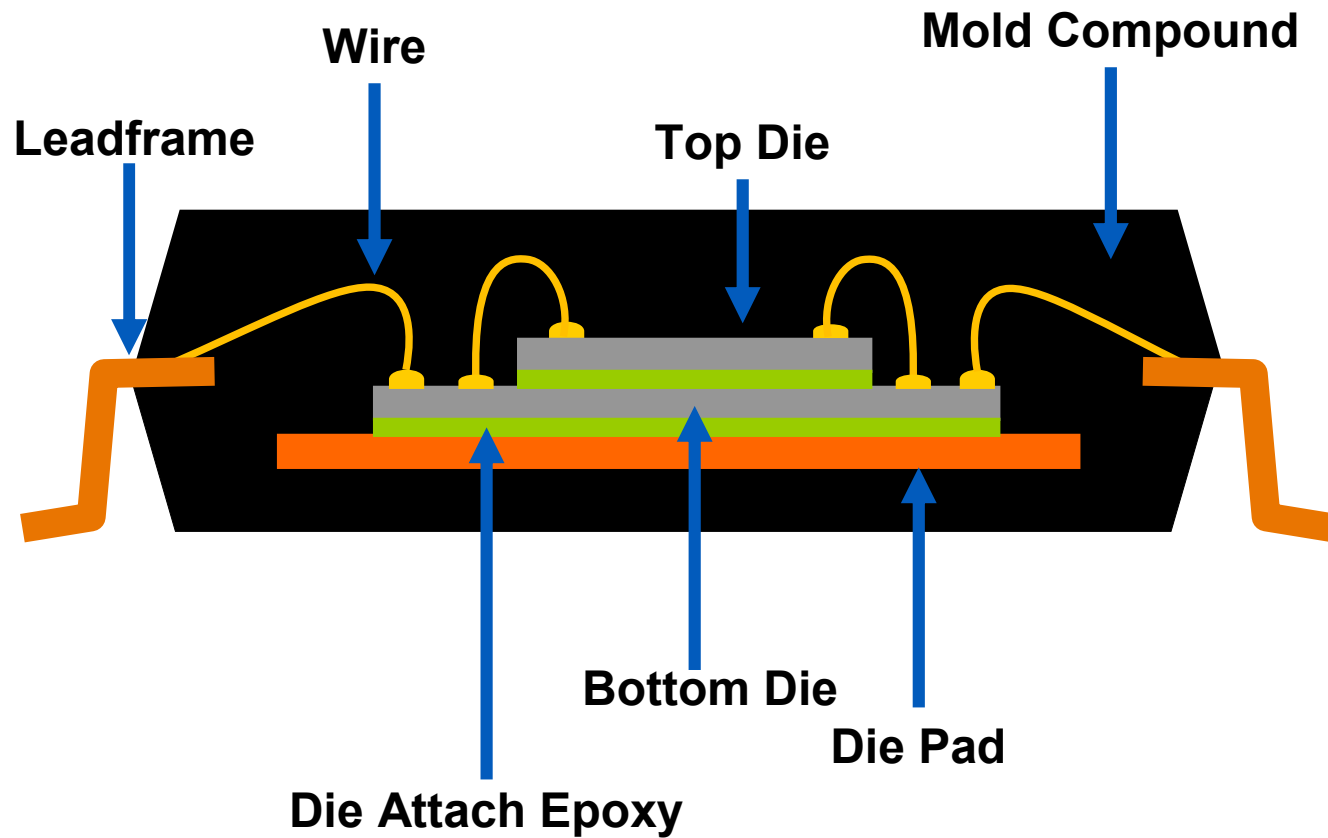
SOIC 28 (STACKED DIE)

PDIP 28 (STACKED DIE)
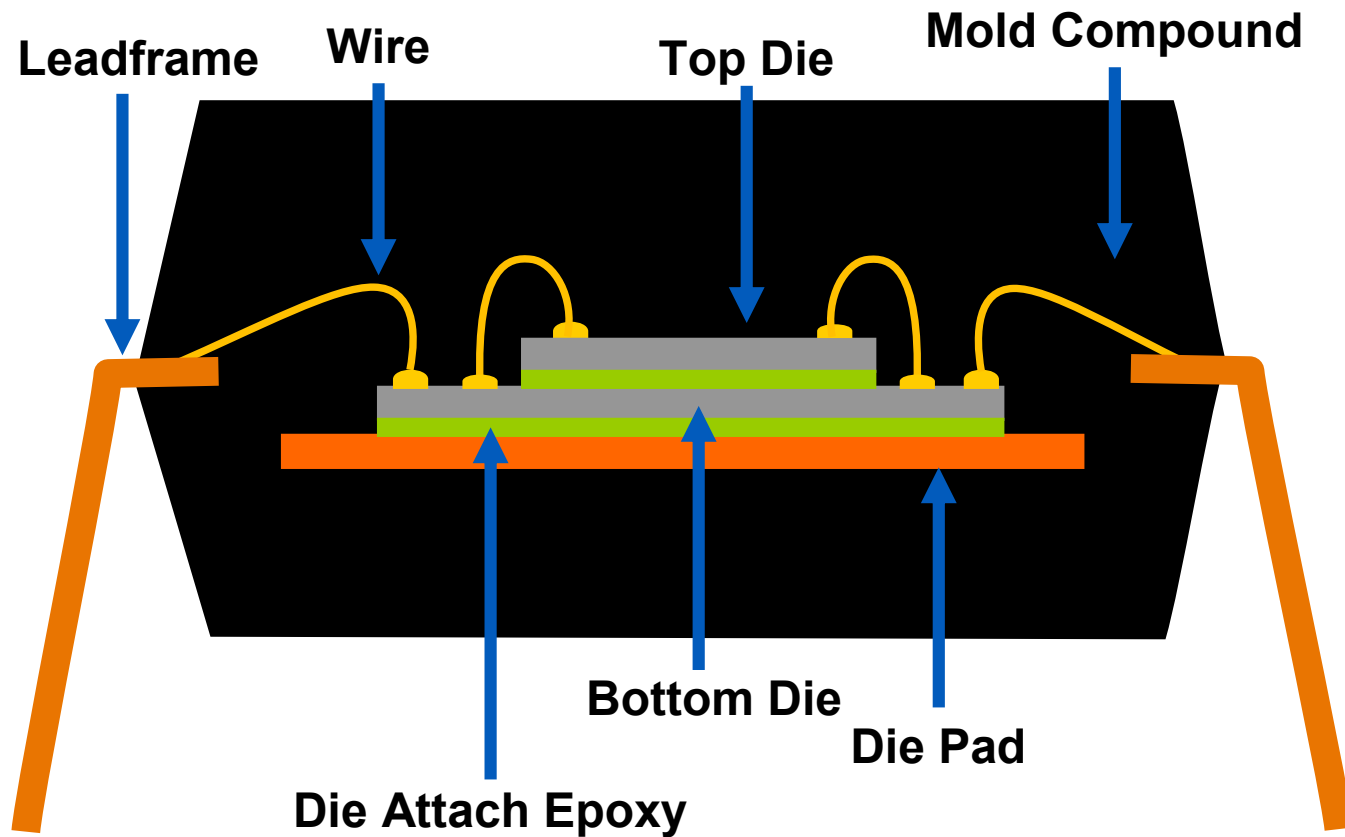
PDIP
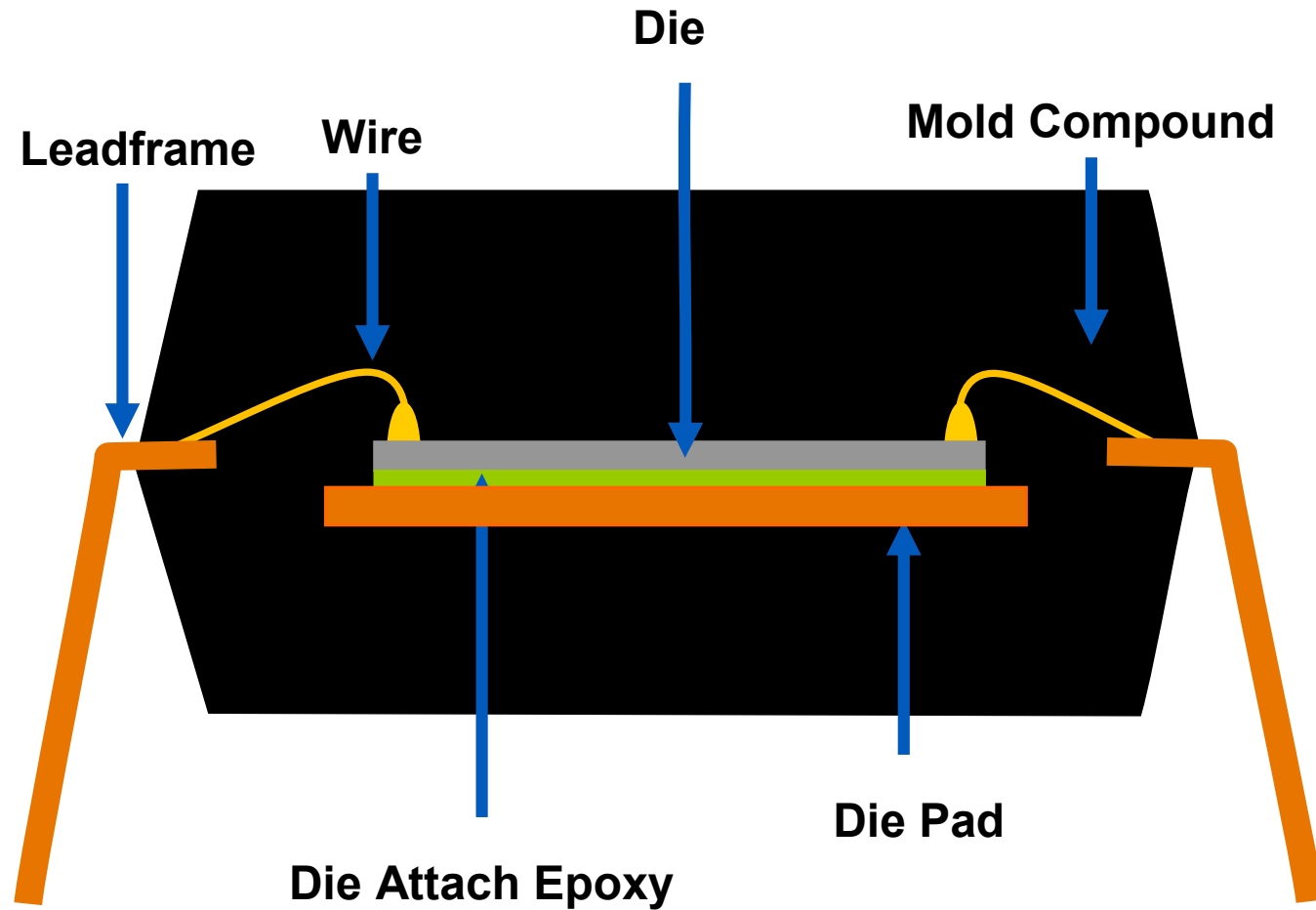
THE END

HISTORY PAGE

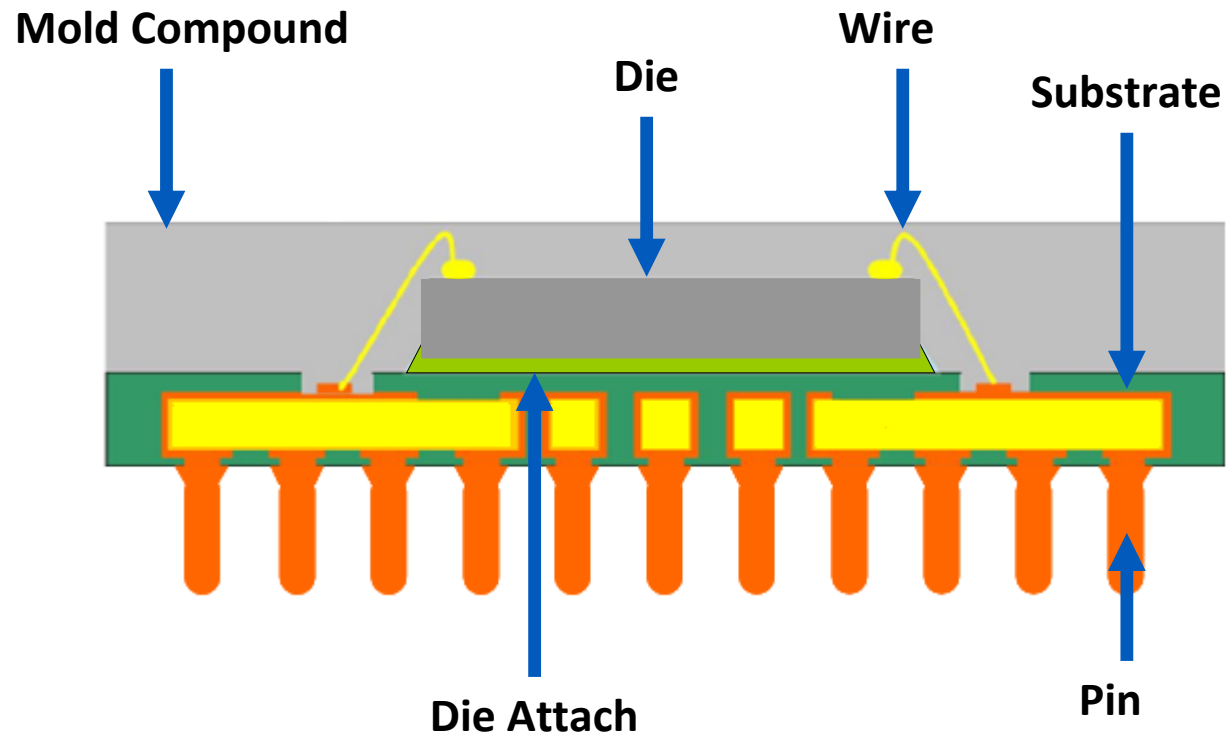| Revision	Owner	Description of Change
**	LMAG	Initial Release
Rev. 1	JARG	1. Added Cross Section Drawing for BGA (STACKED DIE) Package [Page 9] 2. Updated WLCSP Cross Section Drawing [Page 13] 3. Change Document Title from Package Cross - Section to PACKAGE CROSS - SECTION DRAWINGS [Page 1] 4. Add Month and Year on the first page to reflect the date of revision / update [Page 1]
Rev. 2	JARG	1. Added SOIC28 (Stacked Die) Package Cross Section Drawing (Page 17) 2. Added PDIP28 (Stacked Die) Package Cross Section Drawing (Page 18)
Rev. 3	JARG	1. Added Cross section drawing of PDIP Package on (Page 19)